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Contents

vii *Conference Committee*
xi *Organizers, Sponsors, and Cooperating Partners*

1ST PLENARY

14508 02 **Imaging near the resolution limit: from Abbe's theory on microscopy to high-NA EUV lithography (Keynote Paper)** [14508-101]

SIMULATION METHODS AND OPC/ILT MASK CORRECTIONS

14508 05 **Curvilinear MRC mask verification methodology** [14508-42]

14508 07 **Simulation model for maskless lithography based on digital mirror devices** [14508-15]

WAFER LITHOGRAPHY AND PATTERNING

14508 09 **E-beam cell projection for 3D blazed gratings and curvilinear features** [14508-39]

14508 0B **Automated cell projection detection and positioning for advanced electron beam lithography applications** [14508-59]

NANO-IMPRINT LITHOGRAPHY AND PHOTONICS

14508 0F **Investigations on the nano-imprint process for large-area pulse compression gratings** [14508-14]

14508 0I **Immersion lithography process tuning for line edge roughness optimization: photonic waveguides applications** [14508-25]

3RD PLENARY

14508 0J **Mask technologies: active controller for the semiconductor business (Invited Paper)** [14508-100]

EUV LITHOGRAPHY I

14508 0K **Metal-oxide resist height variations through pitch in EUV lithography** [14508-76]

14508 0L **Exploring frequency doubling in EUVL: solutions and limitations** [14508-18]

14508 0M **Systematic study of vector- and pixel-based MPC for curvature control in high-NA EUV masks** [14508-50]

14508 0N **Enhancements of EUV optics at ZEISS and future developments** [14508-21]

EUV LITHOGRAPHY II

14508 0Q **Understanding MOR pattern density sensitivity and its mitigation through process optimization** [14508-22]

14508 0R **EUV holography: a new patterning mode for the PSI interference lithography facility (Invited Paper)** [14508-41]

POSTER SESSION

14508 0T **Potential of maskless exposure tool: evaluation and analysis for MEMS applications** [14508-8]

14508 0U **Stacked grayscale lithography using intra-level e-beam exposure on latent resist image of i-line structures using specialized data preparation methods** [14508-54]

14508 0X **Sub-resolution circular nanopillar fabrication via layout tone inversion and geometry optimization by VSB electron beam lithography in a 300mm CMOS clean room** [14508-55]

14508 0Y **Investigation of anamorphic reductions in hyper-NA EUV** [14508-43]

14508 10 **Decoupling mask and EUV lithography scanner contributions to contact-hole stochastic LCDU** [14508-75]

14508 12 **Improving etching and imaging performance of Pt-based EUV mask absorbers by metal ion implantation** [14508-7]

14508 15 **Elitho: an open-source high-NA EUV lithography simulator** [14508-6]

14508 16 **Fixing non-convergent Born series through Rachford splitting** [14508-17]

14508 17 **Performance of MBM-2000C, a multi-beam mask writer for mature nodes** [14508-35]

14508 1A **Recipe for detecting mask house CD metrology mismatch using wafer dose-to-size for 130nm node manufacturing** [14508-11]

14508 1C **AIMS AutoAnalysis: the highly utilized standard for automated defect review on aerial images** [14508-67]

14508 1E **The particle removal tool: dry cleaning of advanced photomasks** [14508-60]

14508 1F **Annotation-free defect detection in SEM images of contact holes using generative diffusion** [14508-73]

14508 1G **Machine-learning-based 3D sidewall reconstruction of line/space patterns from 2D SEM images** [14508-74]

SUSTAINABILITY & PMJ 2026 BEST POSTER

14508 1I **Sustainability as an innovation driver for semiconductor manufacturing and R&D engineering (Invited Paper)** [14508-5]

MASK AND TEMPLATE MANUFACTURING

14508 1J **Extending laser mask writers to curvilinear photomask applications** [14508-47]

14508 1K **Fabrication of nanoimprint templates for scalable and shape-flexible patterning** [14508-57]

14508 1L **Multi-beam mask writer MBM-4000: enhancements for productivity** [14508-12]

14508 1M **MBMW-401: high-performance multi-beam mask writer for high-NA EUV** [14508-48]

MASK INSPECTION AND METROLOGY I

14508 1O **New development in EUV photomask metrology and inspection (Invited Paper)** [14508-68]

MASK INSPECTION AND METROLOGY II

14508 1R **CD-SEM-based analysis for special pattern placement characterization in next-generation EUV mask manufacturing** [14508-56]

14508 1S **High precision curvilinear metrology and design-based metrology technologies for Advantest's mask CD SEM** [14508-38]

14508 1T **EUV mask defectivity assessment through PDM characterization study (Part I)** [14508-31]

14508 1U **Non-destructive characterization of a EUV mask via machine-learning-enabled scatterometry using a table-top 13.5nm HHG source** [14508-10]

CONTAMINATION CONTROL

14508 1W **Material degradation-induced dose shift in advanced lithography: the role of mask oxidation** [14508-4]